Part A General Servicing Procedures

This part of the manual is divided into the sections listed below. These sections provide some general and advisory information on servicing procedures, a brief history of T800 programming software, and a list of Technical Instructions pertaining to T830 Series equipment.

Section	Title	Page
1	**General**	**1.1**
1.1	Caution: CMOS Devices	1.1
1.2	Caution: Beryllium Oxide & Power Transistors	1.2
2	**Mechanical**	**2.1**
2.1	Pozidriv Recess Head Screws	2.1
2.2	Disassembly/Reassembly	2.1
3	**Component Replacement**	**3.1**
3.1	Leaded Components	3.1
3.1.1	Desoldering Iron Method	3.1
3.1.2	Component Cutting Method	3.1
3.2	Surface Mount Devices	3.2
4	**To Remove Cased Mica Capacitors**	**4.1**
5	**Software History**	**5.1**
5.1	BASEPROG V1/PGM800 V2	5.1
5.2	PGM800 V2.01	5.1
5.3	PGM800 V2.21	5.2
5.4	PGM800Win V1.00	5.2
6	**Technical Instructions**	**6.1**

Figure	Title	Page
1.1	Typical Anti-static Bench Set-up	1.1

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